Vintage: Dec. 2009
Wafer Size: 300mm
SW Version: 5.1.0.b
Main Process: Photo
Sub-Process: ARF-Scanner

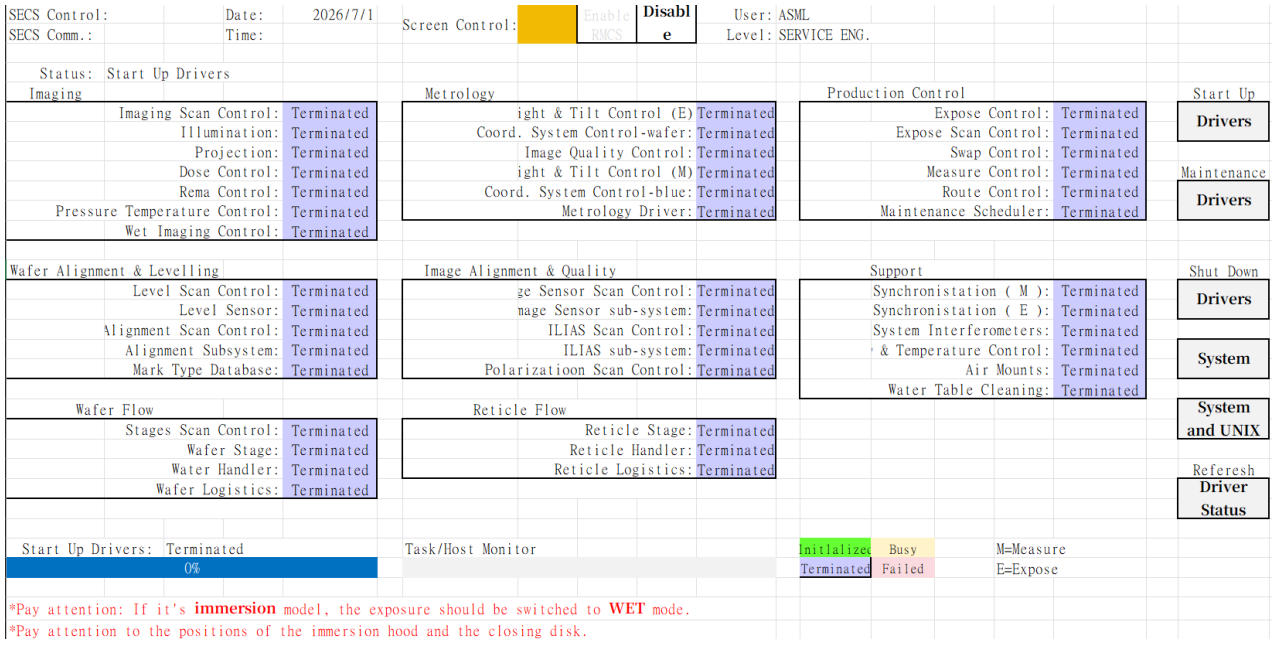
(2) Hardware Configuration:

	Moudule	Check Items	Yes or No	Remarks
1	OIU	Is the motherboard complete?	✓	
2		Are the keyboard, mouse, and monitor working	✓	
3	WH	Hardware defects or damage	X	
4		Are there any scratches or dirt on the component gripper or TSU surface?	X	
5	WS	Hardware defects or damage	✓	hover sensor valve connector damaged
6		Are there any scratches or dirt on the surface of the component Closing Disk?	X	attached on holder
7		Are there any scratches or dirt on the surface of the mirror block components?	X	
8		Are there any scratches or dirt on the Z-mirror component surface?	✓	water stain
9		Are there any scratches or dirt on the surface of the image sensor components?	X	
10		Are there any scratches or dirt on the surface of the wafer table component?	X	wafer on table
11	RH	Hardware defects or damage	X	
12	RS	Hardware defects or damage	X	
13		Are there any scratches or dirt on the R-chuck component surface?	X	A little bit of particle
14	ILL	Hardware defects or damage	X	
15		Does the surface of the REMA lens have any scratches or dirt?	X	
16		Is there a number of Bending Points?	X	

17	Lens	Hardware defects or damage	X	
18		Are there any scratches or dirt on the top and bottom of the lens?	X	
19		Is the sensor on the top of the lens complete?	✓	
20	EIM	Hardware defects or damage?	X	
21		Hardware defects or damage?	✓	295
22	LMA&AOM	Hardware defects or damage?	X	
23	ELEC	Hardware defects or damage?	X	
24	WSRC	Hardware defects or damage?	X	
25	RSRC	Hardware defects or damage?	X	
26	ACC	Hardware defects or damage?	X	
27	LCWC	Hardware defects or damage?	X	
28	MCWC	Hardware defects or damage?	X	
29	WICC	Hardware defects or damage?	X	
30	WISC	Hardware defects or damage?	X	
31	Laser	Hardware defects or damage?	X	MODEL: Cymer XLA360 2005 10/31

(3) Status of System:

System safely powered down_



(4) System Acceptance Test:

Full dynamic testing omitted due to the tool's safely decommissioned status and utility isolation; comprehensive initialization and calibration deferred to the final installation phase

TWINSCAN XT:1700Fi SYSTEM ACCEPTANCE TESTS

Category	Items	Spec	Model: XT1700Fi
	Full Acceptance Test	XT1700Fi	Result-Data
1. Overlay	1.1 Single machine overlay	≤ 5	NA
2. Intensity	2.1 Slit integrated power, 11 scans in 26mm Setting 1 [mW/cm]	≥ 1650**	NA
3. Projection Lens	3.1 RMS Z5-Z37 [nm]	≤ 1.4	2.03
	3.2 RMS Spherical [nm]	≤ 0.8	0.88
	3.3 RMS coma [nm]	≤ 0.8	0.46
	3.4 RMS astigmatism [nm]	≤ 0.8	0.55
	3.5 RMS 3-foil [nm]	≤ 0.8	0.56
	3.6 Long range straylight [SAMOS %]	≤ 0.9	NA
	3.7 Short range straylight [SAMOS %]	≤ 1.2	NA
4. Illumination	4.1 Dose system performance, setting 1 [%]	≤ 1.0	NA
	4.2 Integrated slit uniformity, setting 1 [%]	≤ 0.30	NA
	4.3 Integrated scan uniformity, setting 1 [%]	≤ 0.2	NA
	4.4 Dose repeatability [%]	≤ 0.2	NA
	4.5 Dose accuracy setting 1 [%]	± 0.7	NA
5. Pupil Verification	5.1 Ellipticity, Setting 1 [|meam|]	≤ 1.5	NA
	5.2 Sigma variation setting 1 [range]	≤ 0.007	NA
6. Focus and Leveling	6.1 Wafer map repeatability (99.7%) [nm]	≤ 8	NA
7. Dynamic Performance	7.1 MA X&Y (mean+3ig) [nm]	≤ 2.0	NA
	7.2 MSD X&Y (max of mean per field) [nm]	≤ 6.5	NA
	7.3 Inspection time (<200 particles found) [nm]	≤ 225	NA
	7.4 Size accuracy - lates spheres () Upper surface		
	10um [um]	± 3	NA
	30um [um]	± 3	NA
	50um [um]	± 5	NA
	7.5 Size accuracy - latex spheres () Lower surface		
	10um [um]	± 3	NA
	30um [um]	± 3	NA
	50um [um]	± 5	NA
8. BMWL - fine	Test results		NA
9. TSPE	Test results		NA
10. SWZS	Test results		NA